

MALS062

Silicon planar type

For ESD protection

■ Features

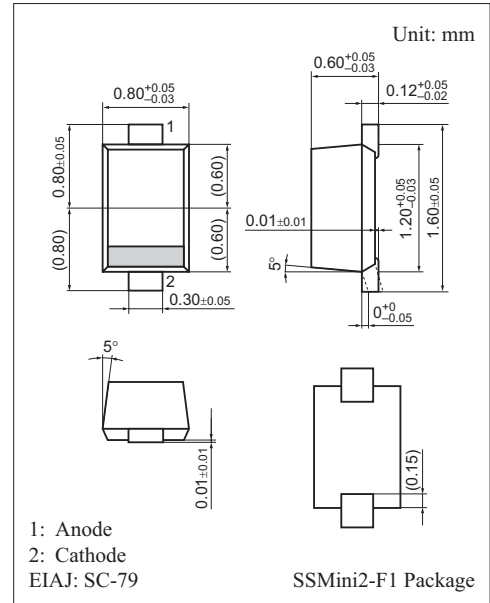
- Electrostatic discharge ESD: ± 30 kV
- SS-Mini 2 pin molde type package, optimum for high-density mounting.

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	P_T	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$
Electrostatic discharge *2	ESD	± 30	kV

Note) *1: $P_T = 150$ mW achieved with a printed circuit board.

*2: Test method: IEC61000-4-2

(C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

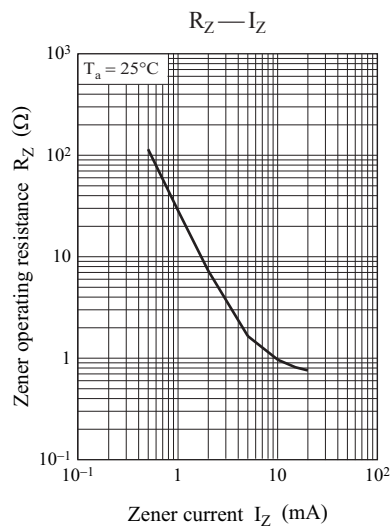
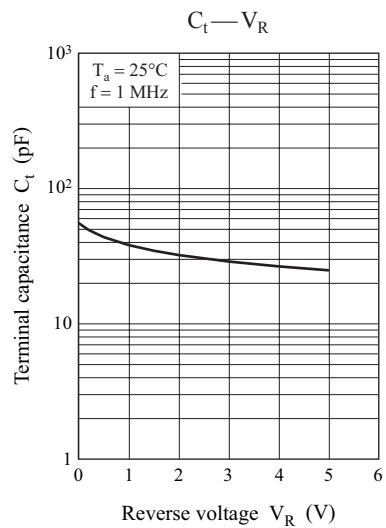
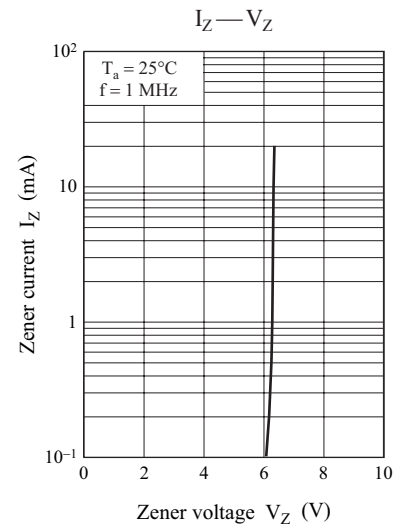
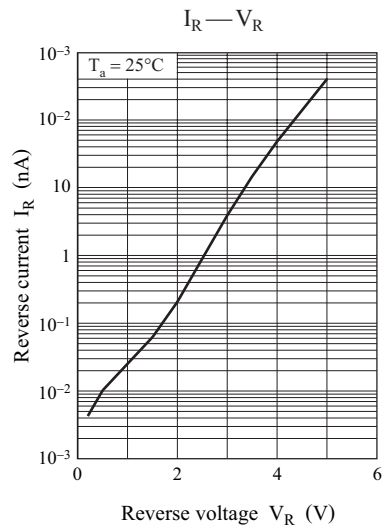
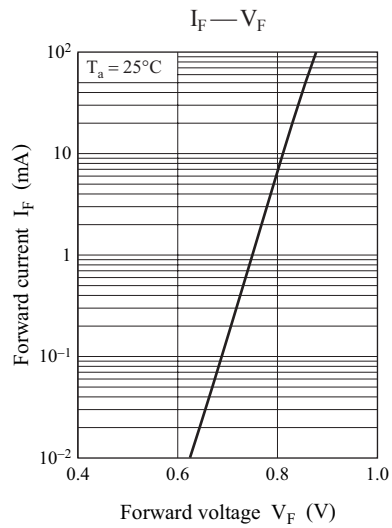
Marking Symbol: DE

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakdown voltage *	V_{BR}	$I_Z = 1$ mA	5.8	6.2	6.6	V
Reverse current	I_R	$V_R = 4.0$ V			1.0	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		55		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. The temperature must be controlled 25°C for V_{BR} measurement. V_{BR} value measured at other temperature must be adjusted to V_{BR} (25°C)3. *: V_{BR} guaranteed 20 ms after current flow.



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